ABSTRACT OF THE DISCLOSURE

SEMICONDUCTOR DEVICE, METHOD OF FABRICATING THE SAME, FILM CARRIER TAPE, CIRCUIT BOARD, AND ELECTRONIC APPARATUS

A semiconductor device comprising an insulating film having a device hole, a plurality of bumps formed on the insulating film, a plurality of first leads having end faces thereof exposed on an outline edge of the insulating film, each of the first leads being electroplated and connected with one of the bumps, a plurality of second leads having end portions thereof protruding into the device hole, each of the second leads being electroplated and connected with one of the bumps, and a semiconductor chip connected with the end portions of the second leads in the device hole. The insulating film is outlined to have a cut in a region including each of the exposed end faces of the first leads.

FIG. 1